

1 DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION

2 As the below named inventor, I hereby declare that:

3 My residence, post office address and citizenship are as stated  
4 below next to my name.

5 I believe I am the original, first and joint inventor of the subject  
6 matter which is claimed and for which a patent is sought on the  
7 invention entitled: Methods of Removing at Least Some of a Material  
8 from a Semiconductor Substrate, filed August 31, 2000, as Application  
9 Serial No. 09/653,157.

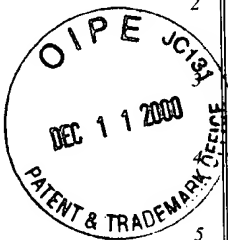
10 I hereby state that I have reviewed and understand the contents  
11 of the above-identified specification, including the claims.

12 I acknowledge the duty to disclose information known to me to be  
13 material to patentability as defined in Title 37, Code of Federal  
14 Regulations §1.56.

15 **PRIOR FOREIGN APPLICATIONS:**

16 I hereby state that no applications for foreign patents or inventor's  
17 certificates have been filed prior to the date of execution of this  
18 declaration.

19 I hereby declare that all statements made herein of my own  
20 knowledge are true and that all statements made on information and  
21 belief are believed to be true; and further that these statements were  
22 made with the knowledge that willful false statements and the like so



made are punishable by fine or imprisonment, or both, under  
Section 1001 of Title 18 of the United States Code and that such willful  
false statement may jeopardize the validity of the application or any  
patent issued therefrom.

\* \* \* \* \*

Full name of inventor: **Kevin J. Torek**

Inventor's Signature: Kevin J. Torek

Date: 11-20-00

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Citizenship: **US**

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\* \* \* \* \*

Full name of inventor: **Garo J. Derderian**

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